

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Keisuke SUZUKI</td> <td>06/12/2012</td> </tr> <tr> <td>Kentaro KADONAGA</td> <td>06/12/2012</td> </tr> <tr> <td>Yoshitaka MORI</td> <td>06/12/2012</td> </tr> </tbody> </table>		Name	Execution Date	Keisuke SUZUKI	06/12/2012	Kentaro KADONAGA	06/12/2012	Yoshitaka MORI	06/12/2012		
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<table border="1"> <tr> <td>Name:</td> <td>TOKYO ELECTRON LIMITED</td> </tr> <tr> <td>Street Address:</td> <td>3-1, Akasaka 5-chome, Minato-ku</td> </tr> <tr> <td>City:</td> <td>Tokyo</td> </tr> <tr> <td>State/Country:</td> <td>JAPAN</td> </tr> <tr> <td>Postal Code:</td> <td>107-6325</td> </tr> </table>		Name:	TOKYO ELECTRON LIMITED	Street Address:	3-1, Akasaka 5-chome, Minato-ku	City:	Tokyo	State/Country:	JAPAN	Postal Code:	107-6325
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CORRESPONDENCE DATA											
<p>Fax Number: (860)286-0115</p> <p>Phone: 860-286-2929</p> <p>Email: usptopatentmail@cantorcolburn.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: CANTOR COLBURN LLP</p> <p>Address Line 1: 20 Church Street</p> <p>Address Line 2: 22nd Floor</p> <p>Address Line 4: Hartford, CONNECTICUT 06103</p>											
ATTORNEY DOCKET NUMBER:	BPL0170US										
NAME OF SUBMITTER:	Jaegyo Jang										
<p>Total Attachments: 2</p> <p>source=Assignment#page1.tif</p> <p>source=Assignment#page2.tif</p>											

OP \$40.00 13524285

ASSIGNMENT

WHEREAS We,

Keisuke SUZUKI of c/o **TOKYO ELECTRON TOHOKU LIMITED, 650 Mitsuzawa, Hosaka-cho, Nirasaki City, Yamanashi 407-0192, Japan,**

Kentaro KADONAGA of c/o **TOKYO ELECTRON TOHOKU LIMITED, 650 Mitsuzawa, Hosaka-cho, Nirasaki City, Yamanashi 407-0192, Japan** and

Yoshitaka MORI of c/o **TOKYO ELECTRON TOHOKU LIMITED, 650 Mitsuzawa, Hosaka-cho, Nirasaki City, Yamanashi 407-0192, Japan** (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

FILM FORMING METHOD AND FILM FORMING APPARATUS

which claims priority to **Japanese Patent Application No. 2011-134623, filed on June 16, 2011** and **Japanese Patent Application No. 2012-087434, filed on April 6, 2012,** and for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, **TOKYO ELECTRON LIMITED** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Japan, having a place of business at **Address: 3-1 Akasaka 5-chome, Minato-ku, Tokyo 107-6325, Japan,** is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any

and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: 2012.6.12

Keisuke Suzuki
Keisuke SUZUKI

Date: 2012.6.12

Kentaro Kadonaga
Kentaro KADONAGA

Date: 2012.6.12

Yoshitaka Mori
Yoshitaka MORI

Date: _____
